

MVR5510AMDANES – NXP Standard

Configuration report for ASILD OTP program ID: AN rev C

Rev. 1.0 - 7/23/2024

Report

1 General description

The VR5510 is an automotive multi-output power management integrated circuit, with focus on Gateway, V2X and Infotainment applications. It includes multiple high efficiency switch mode and linear voltage regulators. It offers external frequency synchronization input and output, for optimized system EMC performance.

The VR5510 includes enhanced safety features, with fail-safe output, becoming a full part of a safety-oriented system partitioning, covering both ASILB and ASILD safety integrity level. It is developed in compliance with ISO 26262 standard.

2 Features and benefits

- 60 V DC maximum input voltage
- Configurable VPRE synchronous buck controller with external MOSFETs.
- Configurable Single/dual-Phase Low voltage buck converters with DVS capability
- Configurable Low voltage integrated synchronous BUCK3 converter
- BOOST converter with integrated low side switch
- 3x linear voltage regulators with configurable Output Voltage
- High voltage linear regulator (HVLDO) with LDO and Switch mode operation
- EMC optimization with frequency tuning, clock synchronization, frequency spread spectrum and slew rate control
- Low power standby mode (40 uA quiescent Current)
- 2x input pins for wake-up detection and battery voltage sense
- Device control via I2C interface with CRC (up to 3.4 MHz)
- Selectable OTP Default configuration

3 Applications

- Automotive Infotainment
- High - End Industrial

4 Ordering information

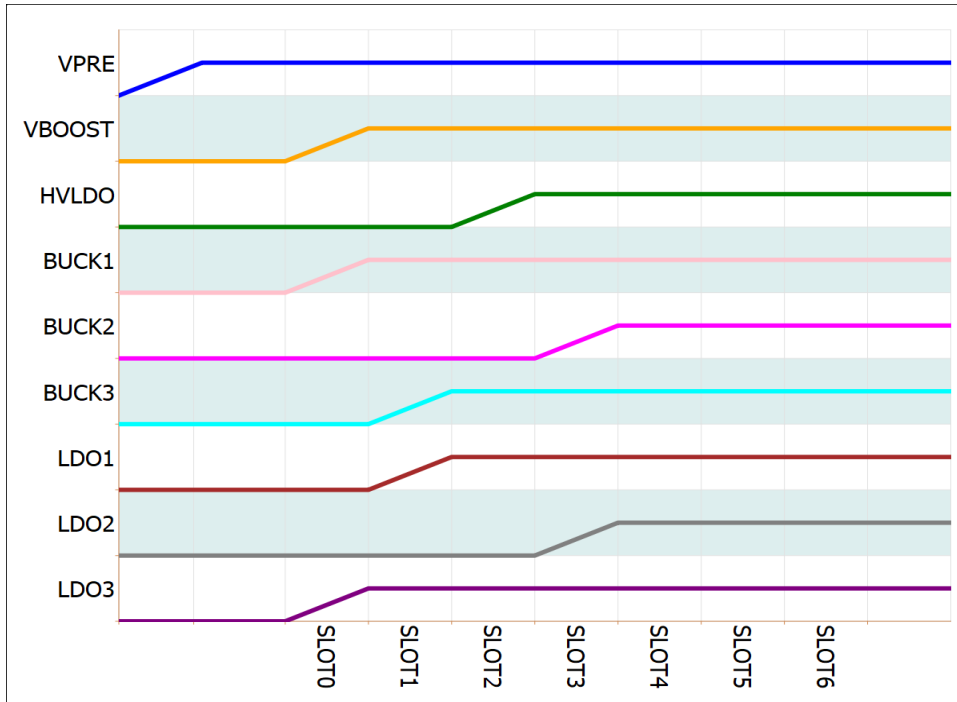
Table 1. Ordering information

Type number ^[1]	Package		
	Name	Description	Version
MVR5510AMDANES	QFN56 EP	QFN56 plastic thermally enhanced very thin quad flat non-leaded package. Wettable flanks; 56 terminals; 0.5mm pitch, 8mmx8mmx0.85mm body	SOT684-21

[1] To order parts in tape and reel, add the R2 suffix to the part number.

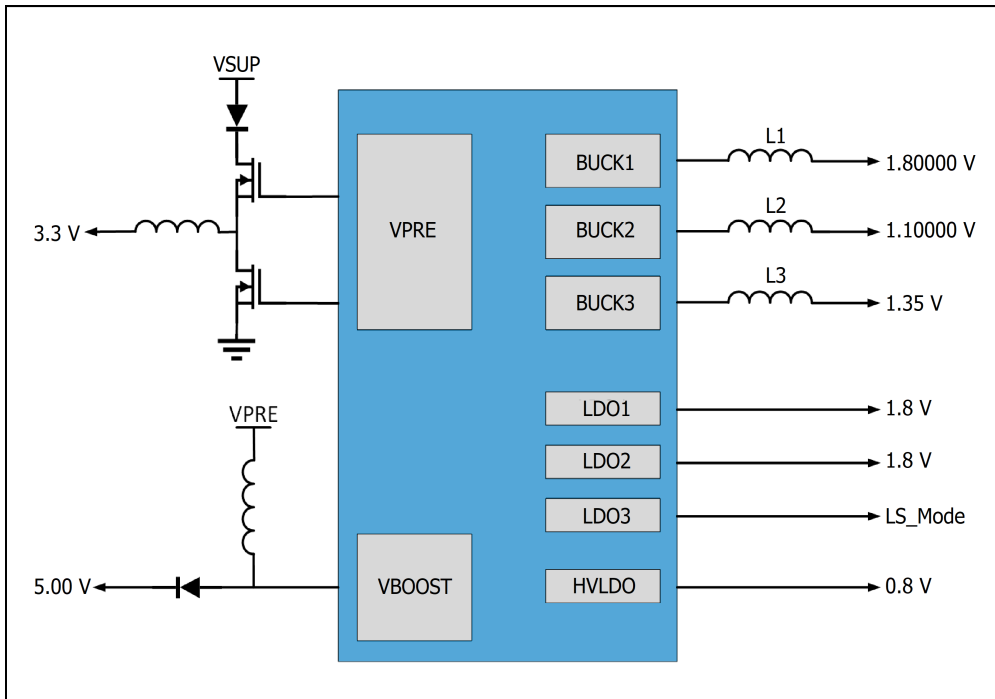


5 Power-up sequence summary



The signals depicted above are enable signals for each regulator. They don't represent the actual ramp voltage.

6 Hardware configuration diagram



7 OTP configuration

See VR5510 datasheet for parametric details. The OTP configuration summary for AN sequence ID is provided in Tables below.

Table 2. Device OTP configuration

Functional block	Feature	OTP selection
Device Configuration	Main I2C Address	0x20
	VSUP UV threshold	4.9 V
	Auto Re-try Enable	Enabled (default)
	Auto Re-try Timeout	4 s (default)
	Number of Retries	Infinite Retry (default)
	PLL Enable	Disabled (default)
	Clock 1 Divider	2.22 MHz (default)
	Clock 2 Divider	455 KHz (default)
	Thermal Warning TH	105 °C (default)
	Deep Sleep Enable	DSM Disabled (default)
IO Configuration	PWRON2 Control	Not Required
	AMUX/FOUT Select	AMUX Enabled (default)
	PSYNC Enable	PSYNC Disabled (default)
	PSYNC Mode	Sync VR5510 + LV PMIC
	PSYNC Power Down Ctrl	Ignore for PwrDown
	Standby Transition Timer	Enabled (default)
	Standby Discharge TH	75 mV (default)
	Standby Polarity	Active Low (default)
	Standby PGOOD Enable	Enabled (default)
PSYNC PGOOD Ext	Enabled	

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	Ext Standby Discharge	Enabled
	Standby PGOOD Delay	400 us
	VDDIO Supply Seletion	LDO3 (default)
	Multiphase Configuration	Single Phase

Table 3. Voltage Regulators Configuration

Functional block	Feature	OTP selection
VPRE Configuration	VPRE Voltage	3.3 V (default)
	Slope Compensation	41.4 mV/us
	VPRE Standby Output Ctrl	Set by VPREV_STBY (I2C)
	ILIM sense Voltage	120 mV
	VPRE HighSide pull down Slew Rate Ctrl	PD/520 mA (455 KHz default value)
	VPRE HighSide pull up Slew Rate Ctrl	PU/520 mA (455 KHz default value)
	VPRE LowSide Slew Rate Ctrl	PU/PD/900 mA (default value)
	Soft Start Ramp	2 mV/us (default)
	VPRE Off Time	80 ns
	TON in PFM	550 ns (default value)
	TON Min	45 ns
	Turn OFF Delay	250 us
VBOOST Configuration	VBOOST Voltage	5.00 V (default)
	Slope Compensation	67 mV/us (default)
	Minimum TON	60 ns (default)
	Current Limit	2.25 A (default)
	Low Side Slew Rate Ctrl	500 V/us (default)
	Input Path to BOS	Enabled (default)

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	Compensation Capacitor	125 pF (default)
	Compensation Resistor	500 KOhm (default)

Table 4. BUCK Regulators

Functional block	Feature	OTP selection
BUCK1 - Single Phase	Output Voltage	1.80000 V
	Current Limit	3.6 A
	Output Inductor	1 uH(default)
	Transconductance	65 umho
	DVS Ramp of BUCK1	9.76 mV/us (power up) / 6.51 mV/us (power down)
BUCK2 - Single Phase	Output Voltage	1.10000 V
	Current Limit	3.6 A
	Output Inductor	1 uH(default)
	Transconductance	65 umho
	DVS Ramp of BUCK2	7.8 mV/us (power up) / 5.2 mV/us (power down)
BUCK3	Output Voltage	1.35 V
	Current Limit	3.6 A
	Output Inductor	1 uH(default)
	R Comp	56 KOhm
	Ramp	3.47 mV/us (power up/down)
	Transconductance	65 umho

Table 5. LDO Regulators

Functional block	Feature	OTP selection
LDO1 Regulator	Output Voltage	1.8 V

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	Current Limit	400 mA (default)
LDO2 Regulator	Output Voltage	1.8 V
	LDO Mode	LDO Mode (default)
LDO3 Regulator	Output Voltage	LS_Mode
	LDO Mode	Load Switch (default)

Table 6. HVLDO Regulator

Functional block	Feature	OTP selection
HVLDO Regulator	HVLDO Voltage	0.8 V (default)
	Sequence Control	Follows HVLDO_OTP slot
	Transition Mode	Switch in Normal / LDO in Standby (default)

Table 7. Voltage Sequence and Timing Configuration

Regulator	Sequence	Enabled	Phase Delay	Clock	TSD Event
VPRE	Auto-enabled	Enabled	No delay	CLK2	
VBOOST	Slot 0	Enabled	No delay	CLK1	Shutdown + DFS
BUCK1	Slot 0	Enabled	1 clock delay	CLK1	Shutdown + DFS
BUCK2	Slot 3	Enabled	2 clock delay	CLK1	Shutdown + DFS
BUCK3	Slot 1	Enabled	3 clock delay	CLK1	Shutdown + DFS
LDO1	Slot 1	Enabled			Shutdown + DFS
LDO2	Slot 3	Enabled			Shutdown + DFS
LDO3	Slot 0	Enabled			Shutdown + DFS
HVLDO	Slot 2	Enabled			Shutdown + DFS
SLOT Width	250 us				

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Table 8. Safety State Machine Configuration

Functional block	Feature	OTP selection
Safety Configuration	FailSafe I2C Address	0x21
	8sec Timer to DFS	Timer Enabled
	ABIST1 to RSTB delay	No Delay (default)
	VCOREMON SVS Clamp Limit	No SVS
	VCOREMON SVS Offset Type	Negative offset (default)
	PGOOD assert with RSTB	PGOOD Asserts with RSTB Fault (default)
	HVLDO Mode Select	Switch Mode (default)
	WDI Polarity	Falling Edge
	WDI on FCCU1	WDI Disabled (default)
	STANDBY Mode	STANDBY Enabled (default)
	STANDBY Polarity	Active Low in standby mode (default)
	STANDBY Request Path	I2C + STBY Pin Transition (default)
	STANDBY Window	STBY Window Enabled (default)
	WD Init Timeout	1024 ms
	Fault Recovery Mode	Enabled
	WD Selection	Challenger WD
	WD Monitoring	WD Enabled (default)
	FCCU Monitoring	FCCU Enabled (default)
	LBIST Enable	LBIST Enabled

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Table 9. Voltage Monitoring

	VMONEN	Voltage	UV_TH	OV_TH	UV Dbnc	OV Dbnc	PGOOD Ctrl	ABIST Ctrl
VCOREMON	Enabled	1.80000 V	95.5 %	104.5 %	25 us	25 us	PGOOD Assigned	ABIST performed
VDDIOMON	Enabled	3.3 V	95 %	105 %	25 us	25 us	PGOOD Assigned	ABIST performed
HVLDOMON	Disabled	0.8 V	93 %	107 %	25 us	25 us	Not Assigned	No ABIST at PWRUP
VMON1	Enabled	0.8 V	95.5 %	106 %	25 us	25 us	PGOOD Assigned	ABIST performed
VMON2	Enabled	0.8 V	97.5 %	104.5 %	25 us	25 us	PGOOD Assigned	ABIST performed
VMON3	Enabled	0.8 V	95.5 %	106 %	25 us	25 us	PGOOD Assigned	ABIST performed
VMON4	Enabled	0.8 V	95 %	105 %	25 us	25 us	PGOOD Assigned	ABIST performed

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